

IN THE CLAIMS

1. (Previously Presented) An integrated circuit (IC) package comprising:
a mold compound, the mold compound having a frame embedded therein, said embedded frame having a top surface, a bottom surface, and a top-to-bottom opening therein;
a lead frame;
a die attached to the mold compound and to the lead frame wherein the embedded frame lies below a periphery of the die; and
a window attached to the mold compound and located above the die to allow light to reach the die.
2. (Original) The IC package of claim 1, wherein the embedded frame substantially comprises ceramic.
3. (Original) The IC package of claim 1, wherein the embedded frame substantially comprises an alloy.
4. (Original) The IC package of claim 3, wherein the embedded frame substantially comprises alloy-42.
5. (Original) The IC package of claim 1 further comprising:
a window frame bordering the window, the window frame having a CTE smaller than that of the mold compound.
6. (Original) The IC package of claim 5, wherein the window frame is made of the same material as that of the embedded frame.
7. (Previously Presented) The IC package of claim 1, wherein the mold compound is a plastic.
8. (Original) An integrated circuit (IC) package comprising:
a mold compound having a ceramic frame embedded therein;

a die having a periphery, wherein the frame lies below the periphery of the die; and

a window having a ceramic frame that is attached to the mold compound and is located above the periphery of the die.

Claims 9-19 (canceled).

20. (Previously Presented) The IC package of claim 1, wherein the die is attached to the lead frame by wire bonds.

21. (Previously Presented) The IC package of claim 7, wherein the die is a color image sensor die.